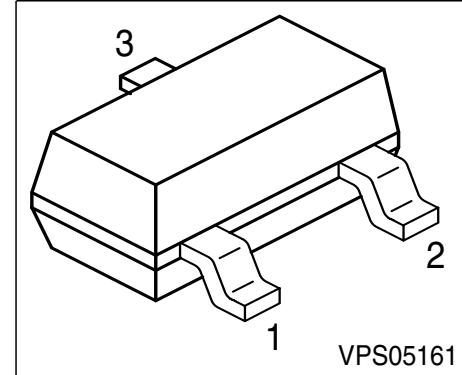


## Silicon Switching Diode

- For high-speed switching applications



Type	Marking	Pin Configuration			Package
BAR 74	JBs	1 = A	2 = n.c.	3 = C	SOT-23

### Maximum Ratings

Parameter	Symbol	Value	Unit
Diode reverse voltage	$V_R$	50	V
Peak reverse voltage	$V_{RM}$	50	
Forward current	$I_F$	250	mA
Surge forward current, $t = 1 \mu s$	$I_{FS}$	4.5	A
Total power dissipation, $T_S = 54^\circ C$	$P_{tot}$	370	mW
Junction temperature	$T_j$	150	$^\circ C$
Storage temperature	$T_{stg}$	-65 ... 150	

### Thermal Resistance

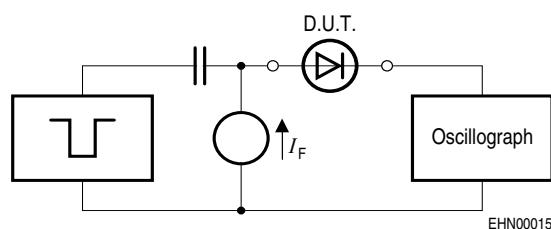
Junction - ambient 1)	$R_{thJA}$	$\leq 330$	K/W
Junction - soldering point	$R_{thJS}$	$\leq 260$	

1) Package mounted on epoxy pcb 40mm x 40mm x 1.5mm / 6cm<sup>2</sup> Cu

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC characteristics</b>					
Breakdown voltage $I_{(BR)} = 100 \mu\text{A}$	$V_{(\text{BR})}$	50	-	-	V
Forward voltage $I_F = 100 \text{ mA}$	$V_F$	-	-	1	
Reverse current $V_R = 50 \text{ V}$	$I_R$	-	-	0.1	$\mu\text{A}$
Reverse current $V_R = 50 \text{ V}, T_A = 150^\circ\text{C}$	$I_R$	-	-	100	
<b>AC characteristics</b>					
Diode capacitance $V_R = 0 \text{ V}, f = 20 \text{ MHz}$	$C_D$	-	-	2	pF
Reverse recovery time $I_F = 10 \text{ mA}, I_R = 10 \text{ mA}, R_L = 100 \Omega$ , measured at $I_R = 1 \text{ mA}$	$t_{rr}$	-	-	4	ns

### Test circuit for reverse recovery time

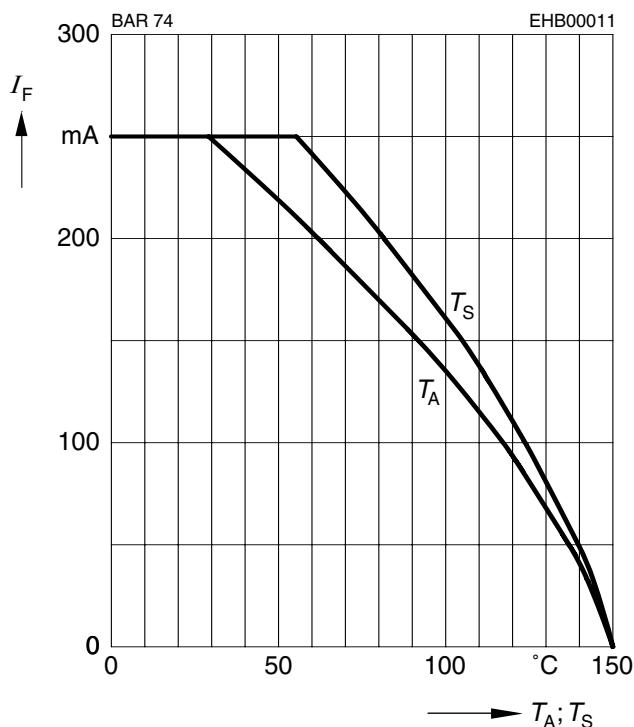


Pulse generator:  $t_p = 100\text{ns}$ ,  $D = 0.05$ ,  
 $t_r = 0.6\text{ns}$ ,  $R_i = 50\Omega$

Oscilloscope:  $R = 50\Omega$ ,  $t_r = 0.35\text{ns}$ ,  
 $C \leq 1\text{pF}$

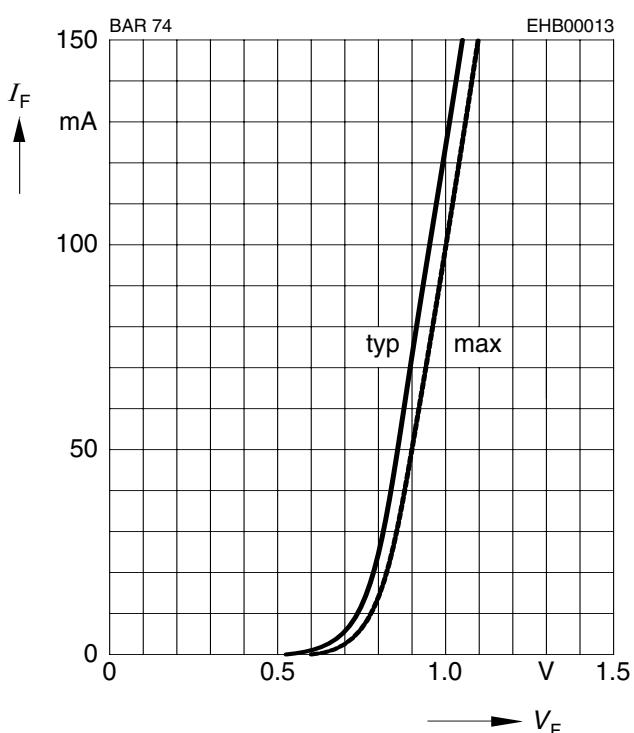
**Forward current  $I_F = f(T_A^*; T_S)$**

\* Package mounted on epoxy

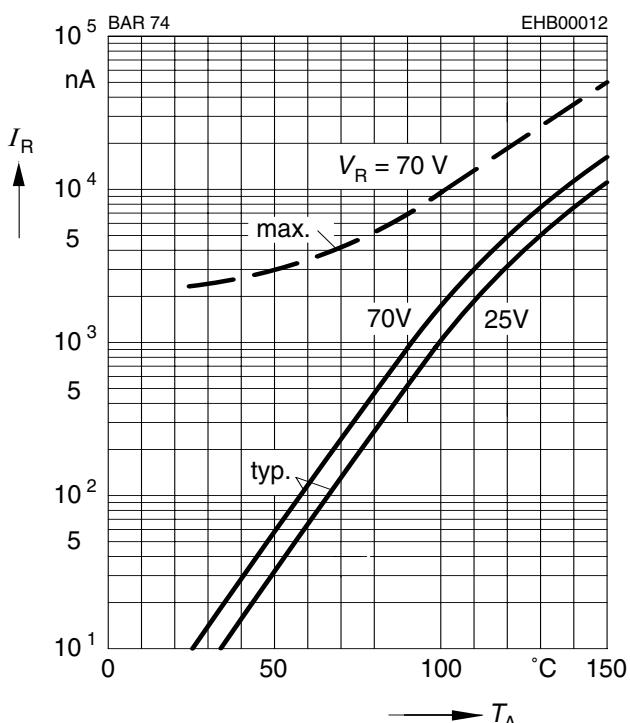


**Forward current  $I_F = f(V_F)$**

$T_A = 25^{\circ}\text{C}$

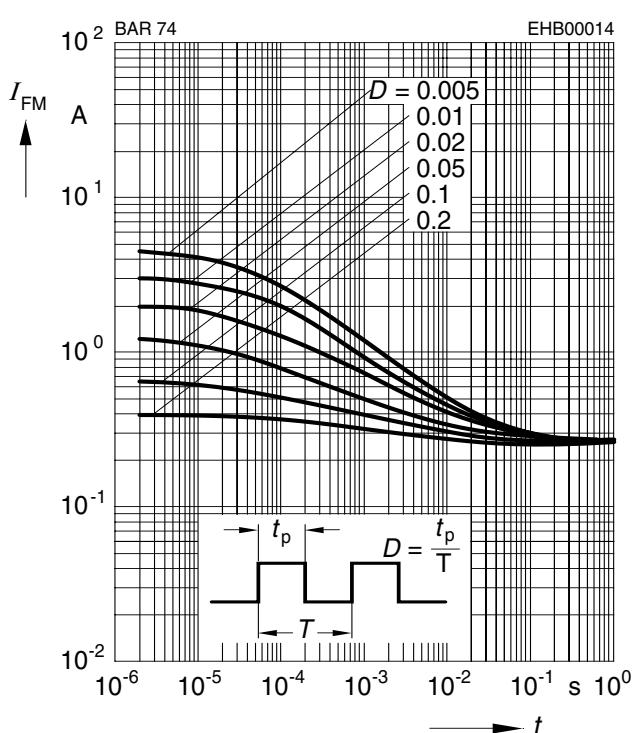


**Reverse current  $I_R = f(T_A)$**



**Peak forward current  $I_{FM} = f(t_p)$**

$T_A = 25^{\circ}\text{C}$



**Forward voltage  $V_F = f(T_A)$**

